The background of the top half of the image is a grayscale, close-up photograph of a printed circuit board (PCB). It shows intricate patterns of copper traces, vias, and pads, creating a complex, geometric texture. The lighting is soft, highlighting the metallic surfaces.

Ucamco



YELO – Mask Adjuster (MAJ)

Webinar August 04, 2020

How does the webinar work?

- All attendees are muted
- Ask questions with the 'Questions' button
- Answers at the end of the webinar
- A copy can be downloaded after the webinar

Who does the work?

- Moderator: Karel Langhout
- Co-Moderator: Sylvia Liemer

Content

- Short Ucamco introduction
- Introduction to YELO Mask Adjuster (MAJ)
- Live demonstration
- Questions and answers

YELO-Mask Adjuster webinar



Ucamco serves the global PCB industry

Laser Photoplotters/Ledia DI

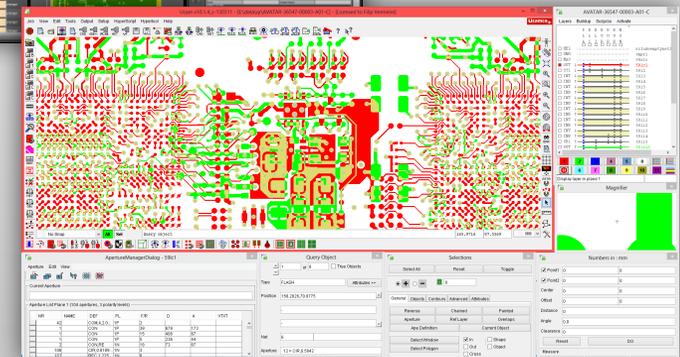
- Best-in-class performance
- Long-term reliability
- Constant evolution

PCB manufacturing software

- Integr8tor, UcamX
- Web-based: iamcam, Communic8tor

PCB bundled front-end software

Gerber developments: X2, X3, Gerber Job



YELO-Mask Adjuster webinar

YELO Mask Adjuster

Parameter Set
YELO-MAJ

Data Preparation
Drill Tool Manager Markup Assistant

Adjust Mask
Ring 0.075 Ignore rings bigger than set value
Copper overhang 0.05
Solder web 0.1 Mask to Mask 0.075
Adjust

Via Handling
 Ignore mask rings larger than set value

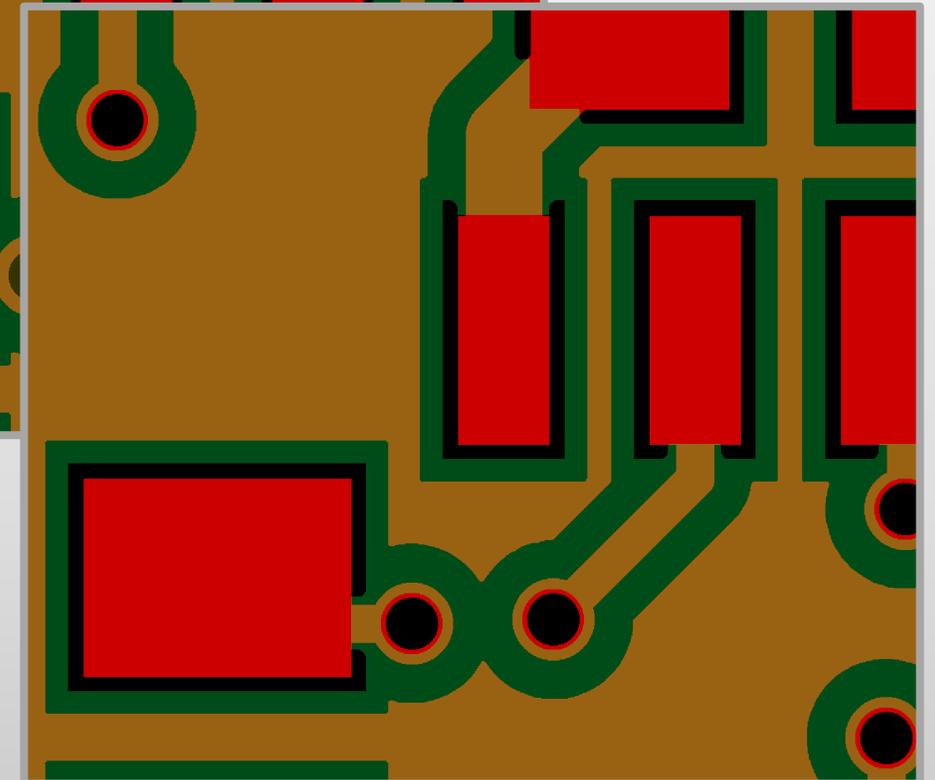
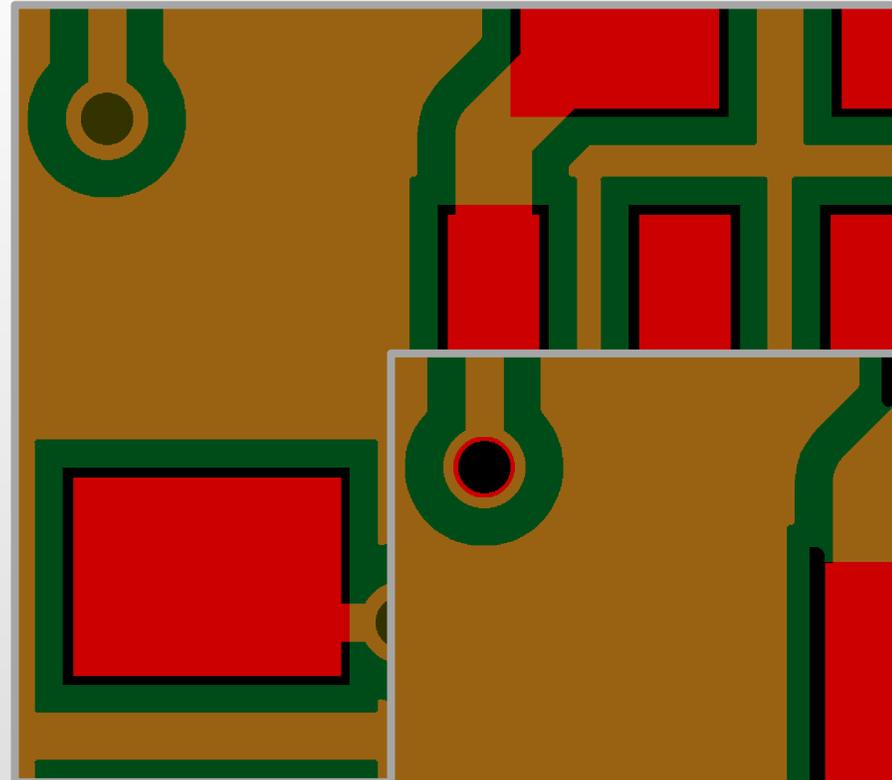
	Reference	Ring +/-
<input checked="" type="checkbox"/> Via with dedicated copper pad free or partially free of mask	<input type="radio"/> Pad <input checked="" type="radio"/> Hole	0.03
<input checked="" type="checkbox"/> Via with dedicated copper covered by mask	<input type="radio"/> Pad <input checked="" type="radio"/> Hole	0.05
<input checked="" type="checkbox"/> Via without dedicated copper pad free or partially free of mask	<input checked="" type="radio"/> Hole	0.075
<input checked="" type="checkbox"/> Via without dedicated copper covered by mask	<input checked="" type="radio"/> Hole	0.1

Apply

Adjust Mask for Embedded Pads
Soldermask ring for in copper pads 0
Soldermask ring reduction if no pad in copper 0
Soldermask ring overlap on tracks 0.025
Clearance soldermask to tracks (transition) 0.05
Adjust

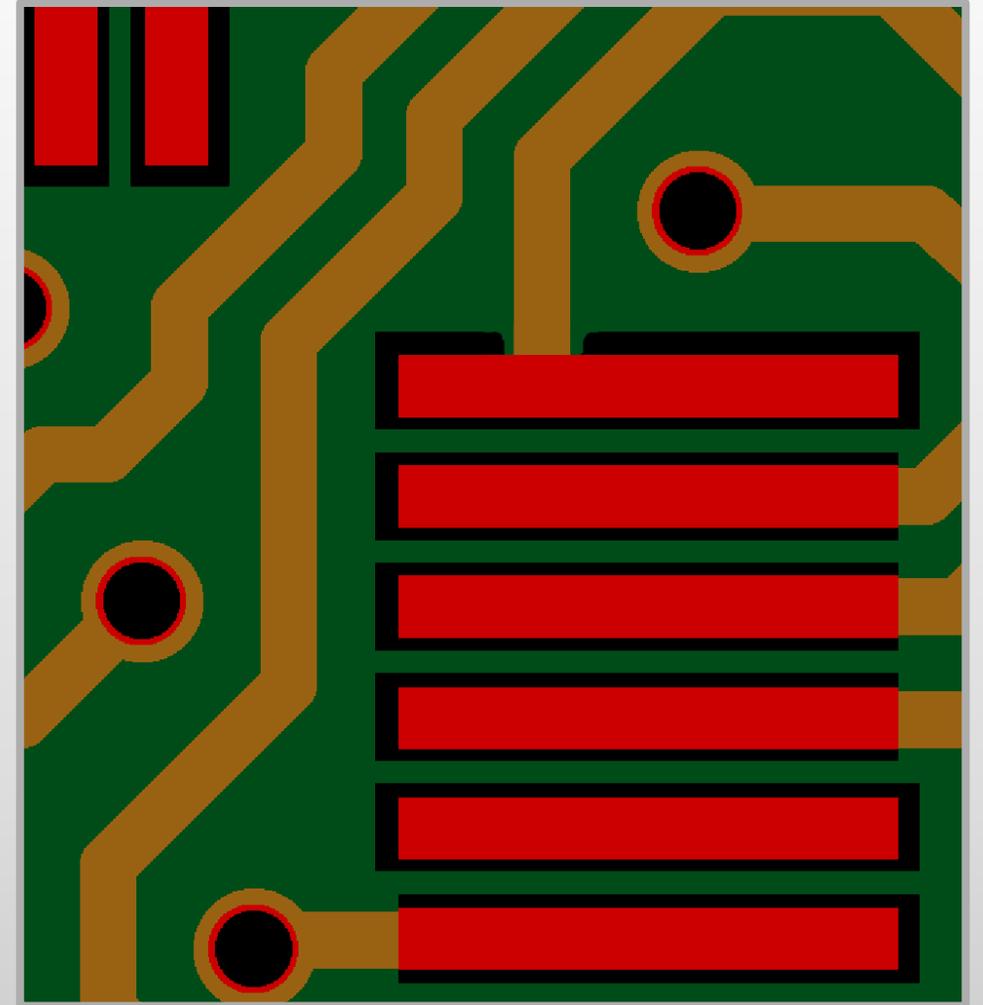
Remodel soldermask (eliminate negatives)
 Backup Original Layers

Apply and Adjust Cancel



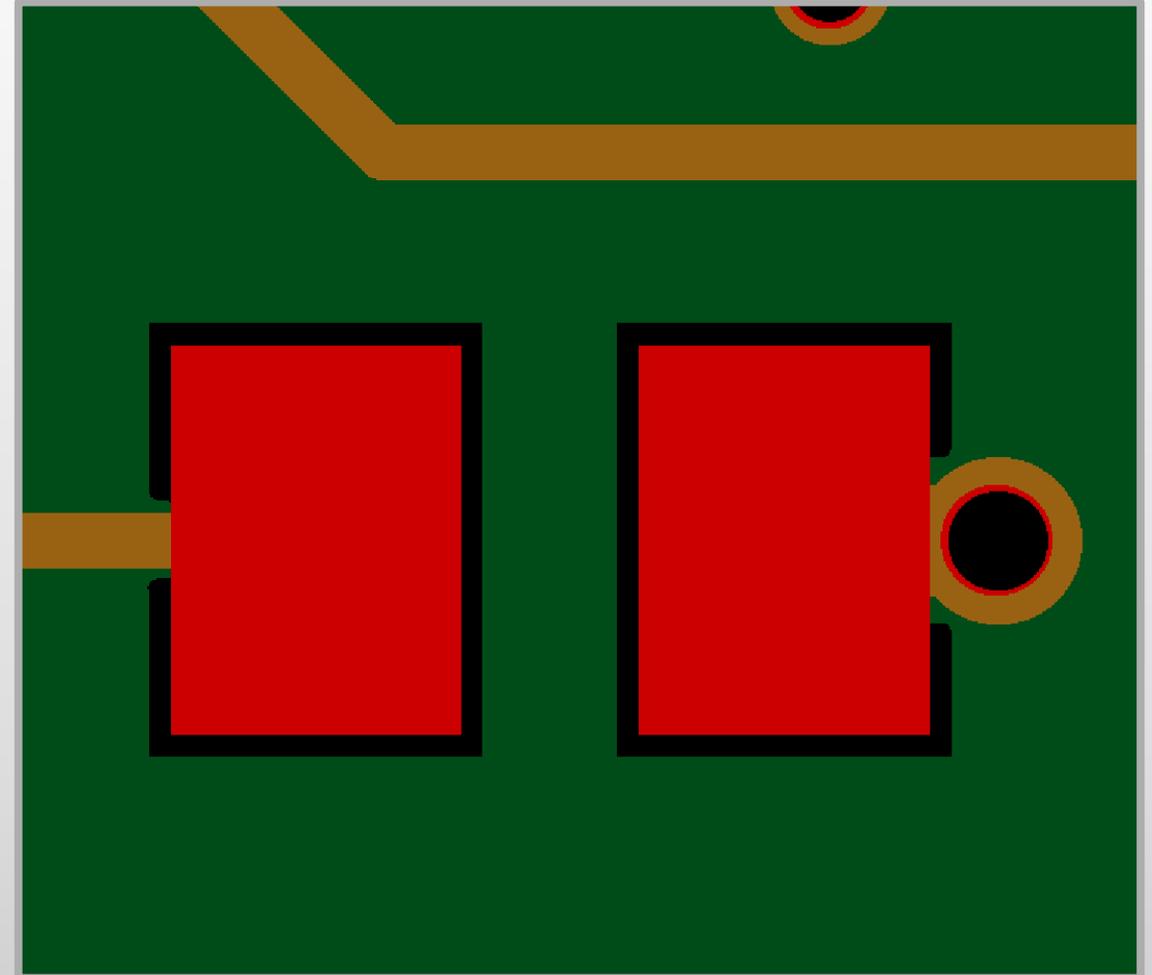
Why adjust a mask?

- Avert mask printed on solder pads
- Prevent solder starvation
- Avoid shorts to foreign copper
- Alleviate the solder mask process
- Reduce manual interventions for assembly procedure
- Meet your customers requirements



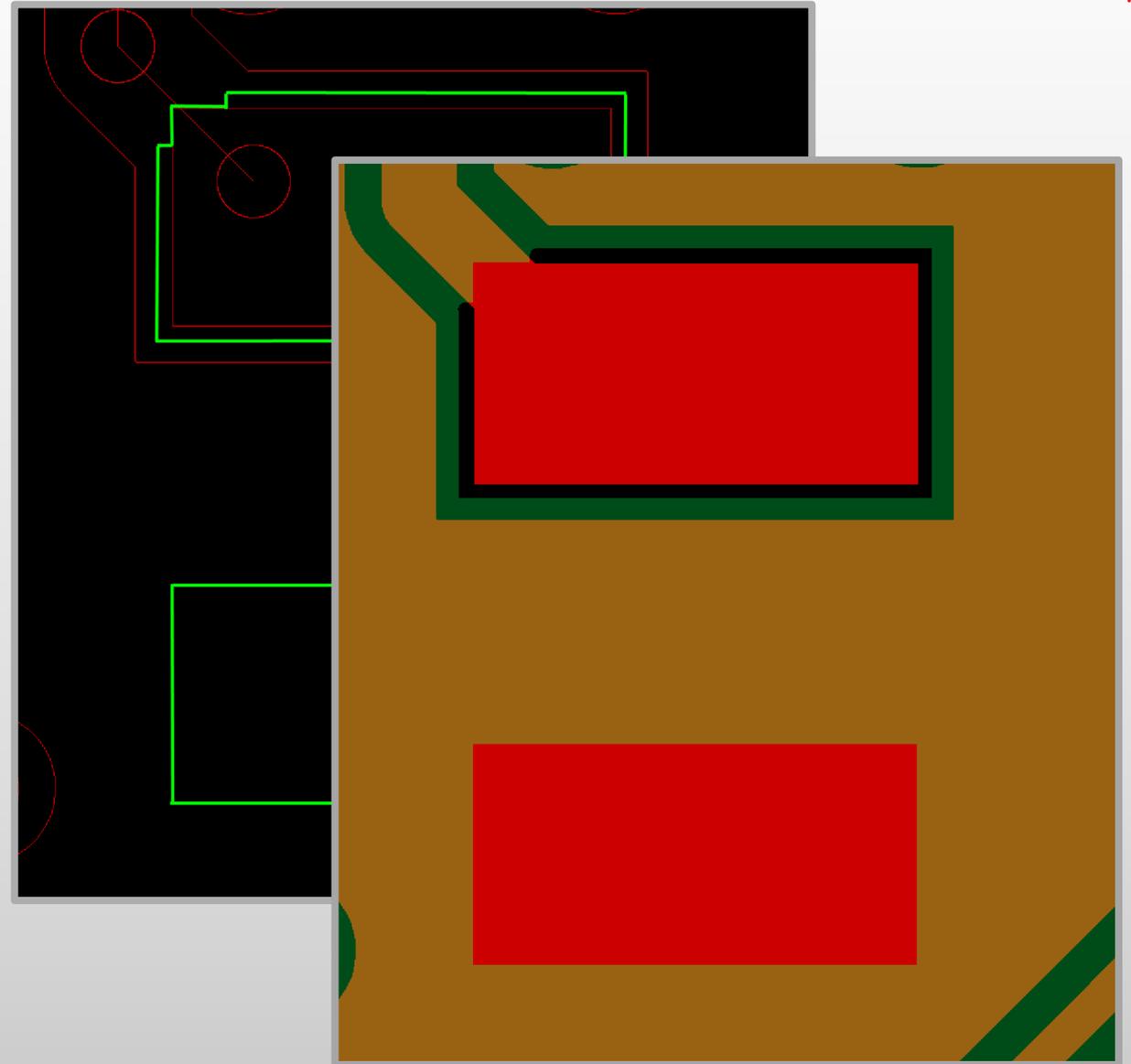
Features

- General adjustments:
 - soldermask ring
 - overhang
 - mask to mask
 - solder web
- Via handling to adjust existing or create new solder mask openings



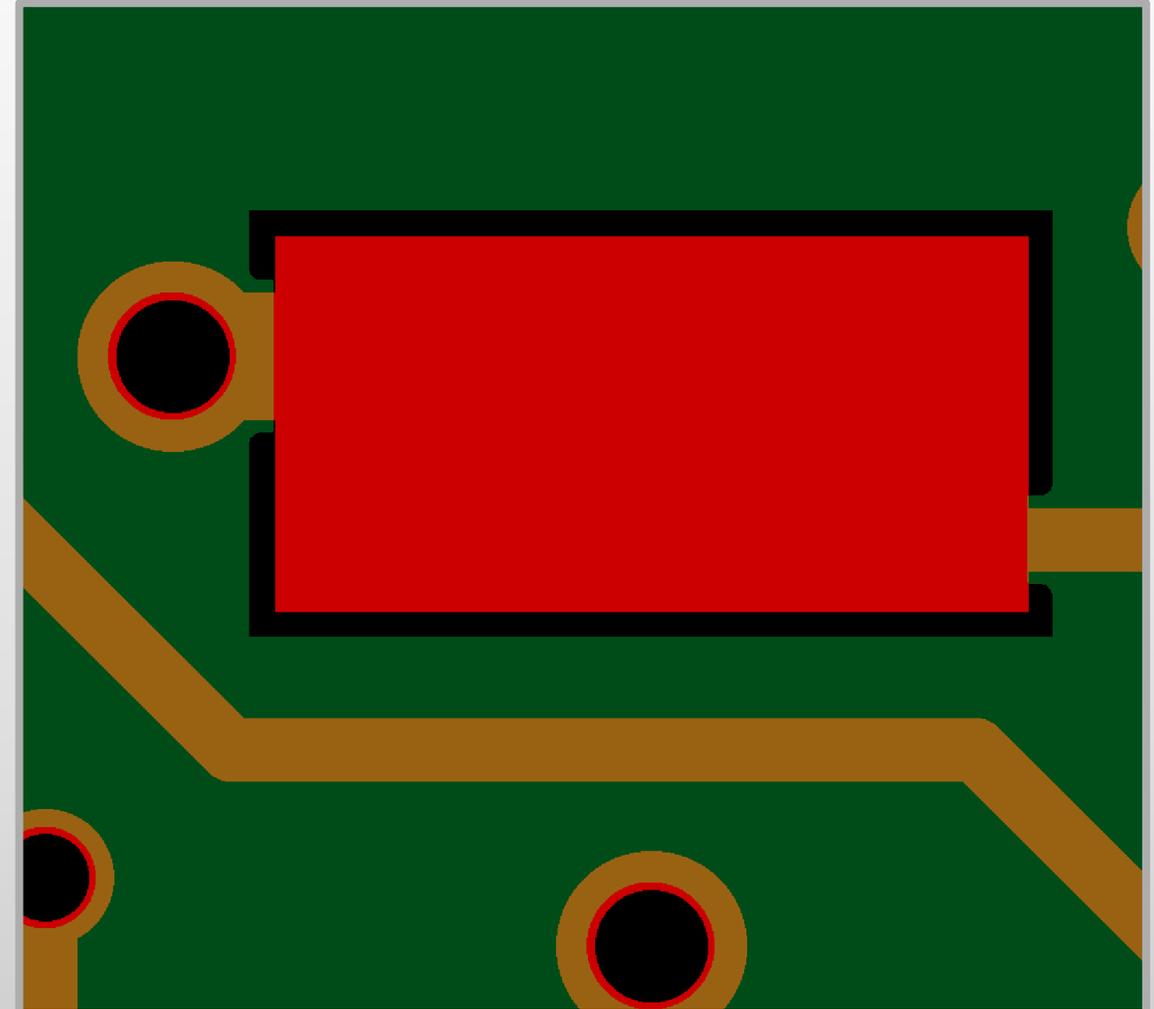
Features

- Equalization of copper surface areas in case some of the solder pads are embedded in copper
- Limit solder paste flow on tracks

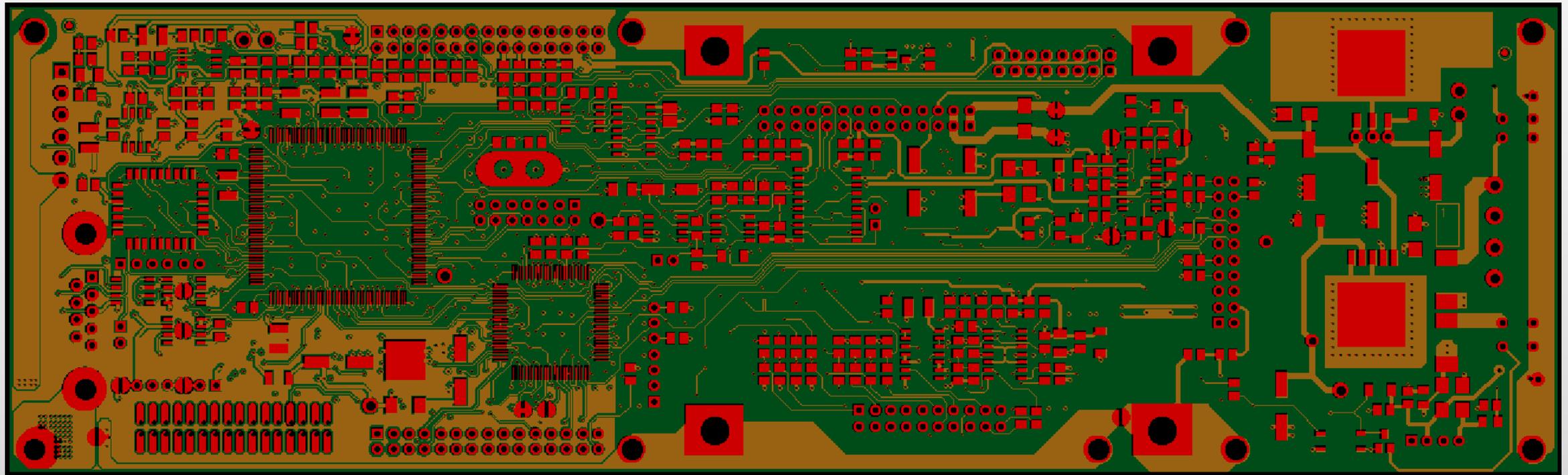


Features

- Comfortable and easy-to-use GUI
- Parameter sets for save and reuse
- Backup layer added for every adjustment step for fast comparison



 **Live demo**



Benefits

- Most comprehensive mask adjuster
- Unrivalled adjustment scope
- Fully automated
- Improvement of mask for the assembly process
- Prevent solder starvation
- Block shorts
- Meet your customers requirements

Thank you!

Interested? Request a trial version at webinars@ucamco.com

Unanswered questions will be answered by email after the webinar

We are looking forward to your feedback.

We will inform you about new webinars

Thank you for attending this webinar.

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